

Amendments to the Claims:

This listing of claims will replace all prior versions, and listings, of claims in the application:

Listing of Claims:

1-16 (canceled)

17. (currently amended) An apparatus, comprising:

an electrically conductive trace on a substrate, the electrically conductive trace including first and second materials, the electrically conductive trace formed by applying a laser beam to the first material disposed on the second material, wherein the laser beam penetrates beyond the first material and into the second material; and diffusing a portion of the first material into a portion of the second material responsive to said applying; and

an inter-layer dielectric material electrically isolating the electrically conductive trace.

18. (previously presented) The apparatus of claim 17, wherein:

the substrate is part of one of a semiconductor package, a printed circuit board, or a die.

19. (previously presented) The apparatus of claim 17, wherein:

the second material includes metal.

20. (original) The apparatus 17, wherein:
the electrically conductive trace includes a copper tin alloy.
21. (original) The apparatus of claim 17, wherein:
the electrically conductive trace is between about 10 microns and about 20 microns in thickness and between about 27 microns and about 35 microns in width.
22. (canceled)
23. (original) The apparatus of claim 17, wherein:
the second material includes copper.
24. (original) The apparatus of claim 17, wherein:
the first material includes tin.
25. (original) The apparatus of claim 17, wherein:
the first material includes an organic material.
26. (original) The apparatus of claim 17, wherein:
the first material includes a conversion coating material.
27. (new) An apparatus, comprising:

an electrically conductive trace on a substrate, the electrically conductive trace including first and second materials, the electrically conductive trace formed by applying a laser beam to the first material disposed on the second material, wherein the laser beam penetrates beyond the first material and into the second material; and diffusing a portion of the first material into a portion of the second material responsive to said applying, and wherein the first material includes an organic material.

28. (new) The apparatus of claim 27, wherein:

the substrate is part of one of a semiconductor package, a printed circuit board, or a die.

29. (new) The apparatus of claim 27, wherein:

the second material includes metal.

30. (new) The apparatus of claim 27, wherein:

the second material includes copper.

31. (new) The apparatus of claim 27, wherein:

the first material includes tin.